Heat Transfer — Japanese Research
Subject Index to Volume 26, 1997

Aerosol particle: **6**, 398-409
Atmospheric pressure: **1**, 16-29

Bioengineering: **8**, 555-567
Boiling: **1**, 16-29; **4**, 291-235
Boiling heat transfer: **8**, 493-514
Boiling onset: **7**, 484-492
Bubble heat transfer: **7**, 484-492

Condensation: **6**, 398-409
Constitutive equation: **2**, 84-96
Contact line: **6**, 360-371
Contact resistance: **6**, 360-371
Convective heat transfer: **7**, 419-434
Cooled cylinder: **7**, 419-434
Corona: **4**, 207-218
Critical heat flux: **1**, 16-29
Critical heat flux (CHF): **6**, 372-384; **7**, 449-458
Critical Rayleigh number: **6**, 385-397
Cross-linked plastic: **3**, 193-206; **4**, 262-274
Cylinder array: **2**, 116-121

Density inversion: **7**, 469-483
Diffusion: **2**, 84-96
Digital image processing: **1**, 54-67
Discharge characteristics: **3**, 193-206
Discharge mechanism: **4**, 207-218
Drag coefficient: **1**, 54-67
Dream pipe: **1**, 39-53

Effective absorption coefficient: **1**, 1-15
Effective thermal conductivity: **3**, 176-192
Electrochemical method: **5**, 332-344
Electrode system: **4**, 207-218
Electronic cooling: **8**, 541-554
Empirical correlation equation: **8**, 493-514
Entropy: **2**, 84-96
Equation of state: **2**, 69-83
Evaporation: **3**, 143-158
Experiment: **3**, 193-206; **4**, 262-274

Film boiling: **4**, 236-248; **7**, 459-468
Fin: **8**, 515-527
Fin array: **8**, 515-527
Finite element method: **6**, 345-359
Fixed bed: **3**, 193-206; **4**, 262-274
Floor heating: **2**, 122-130

Flow pattern: **8**, 493-514
Flow visualization: **1**, 54-67; **2**, 131-142; **5**, 332-344
Fluidized bed: **1**, 54-67; **5**, 306-318
Forced convection: **1**, 16-29; **2**, 97-106; **4**, 236-248, 249-261
Forced-convection boiling: **5**, 292-305
Forced-convection heat transfer: **3**, 176-192
Free convection: **1**, 30-38; **6**, 385-397
Free stream turbulence: **2**, 97-106
Freezing: **2**, 69-83; **7**, 419-434
Frost heave test: **2**, 69-83

Guide gutter: **1**, 30-38

Heat and mass transfer: **2**, 69-83
Heat conduction: **3**, 159-175; **6**, 345-359; **7**, 419-434
Heat conduction analysis: **2**, 107-115
Heat exchanger: **3**, 143-158; **4**, 249-261; **5**, 275-291
Heat-exchanger network: **5**, 275-291
Heat pipe: **2**, 107-115; **8**, 528-540
Heat pump: **2**, 122-130; **6**, 410-418
Heat sink: **8**, 515-527
Heat storage: **2**, 122-130; **6**, 410-418
Heat transfer: **2**, 107-115; **4**, 236-248
Heat transfer augmentation: **6**, 360-371
Heat transfer coefficient: **4**, 262-274
Heat transfer enhancement: **1**, 30-38, 39-53; **5**, 332-344
High subcooling: **1**, 16-29
High-temperature gas-cooled reactor (HTGR): **3**, 159-175
High velocity: **1**, 16-29
Horizontal: **8**, 528-540
Horizontal array: **2**, 116-121
Horizontal cylinder: **2**, 116-121
Horizontal square plate: **1**, 30-38
Horizontal tube bundle: **5**, 306-318
Hot plate: **7**, 435-448
Human thermal model: **8**, 555-567

Immiscible liquids: **8**, 493-514
Inclination angle: **2**, 131-142
Instability: **6**, 372-384
Inverse problem: **6**, 345-359

Jacob number: **8**, 493-514

Latent heat storage: **3**, 193-206
Liquid-liquid direct contact: **8**, 493-514

Marangoni convection: **7**, 469-483
Mass transfer: **8**, 555-567
Material design: **2**, 84-96
Measuring apparatus: **7**, 435-448
Melt-freeze cycle: **4**, 262-274
Micromechanics: **2**, 84-96
Minimum-heat-flux point: **4**, 291-235
Mixed convection: **1**, 39-53
Mixture: **3**, 143-158; **5**, 292-305

Natural circulation loop: **7**, 449-458
Natural convection: **2**, 116-121, 131-142; **3**, 159-175
Network theory: **5**, 275-291
Neutron radiography: **1**, 54-67
Nonequilibrium: **2**, 84-96; **4**, 207-218
Nonhomogeneous porous layer: **3**, 176-192
Nonlocality: **2**, 84-96
Nuclear reactor: **1**, 16-29; **3**, 159-175
Numerical analysis: **2**, 107-115; **3**, 193-206; **4**, 249-261
Numerical simulation: **1**, 39-53
Numerical solution: **6**, 345-359

Offset fins: **4**, 249-261
Optimum clearance: **5**, 332-344
Oscillation: **1**, 39-53; **7**, 449-458

Parallel flow: **8**, 493-514
Particle behavior: **5**, 306-318
Pipeline: **5**, 275-291
Plasma: **4**, 207-218
Polar material: **2**, 84-96
Porous medium: **2**, 69-83
Porous surface: **6**, 385-397
Power semiconductor: **2**, 107-115
Prandtl number: **8**, 493-514
Process control: **5**, 275-291
Process dynamics: **5**, 275-291

Refrigerant: **3**, 143-158
Regularization: **6**, 345-359
Reliability: **2**, 107-115
Removal: **6**, 398-409
Roll casting: **6**, 360-371

Segregation: **2**, 69-83
Semicircular enclosure: **2**, 131-142
Silent discharge: **4**, 207-218
Slit: **1**, 30-38
Solar energy: **1**, 1-15
Solidification: **2**, 69-83; **6**, 360-371; **7**, 469-483
Space station: **4**, 249-261
Spectral transmittance: **1**, 1-15
Spherical particle layer: **3**, 176-192
Spray cooling: **4**, 236-248
Square pulsed voltage: **4**, 207-218
Stability: **6**, 360-371
Stability of vapor film: **4**, 291-235
Stanton number: **8**, 493-514
Streamer: **4**, 207-218
Subcooled boiling: **7**, 459-468
Subcooled film boiling: **4**, 291-235
Subcooled liquid film: **4**, 236-248
Surface tension: **7**, 469-483

Temperature boundary layer: **3**, 176-192
Temperature distribution: **2**, 107-115
Thermal conductivity: **7**, 435-448
Thermal design: **8**, 541-554
Thermal energy storage: **4**, 262-274
Thermal engineering: **4**, 249-261
Thermal radiation: **1**, 1-15; **3**, 159-175
Thermodynamics: **2**, 84-96
Thermophysical property: **1**, 1-15
Thermosyphon: **6**, 372-384
Total transmittance: **1**, 1-15
Transient conduction: **8**, 541-554
Turbulence model: **2**, 97-106
Turbulence promoter: **5**, 332-344
Turbulent boundary layer: **2**, 97-106
Two-phase flow: **3**, 143-158

UA factor: **8**, 493-514

Vertical plate: **6**, 385-397
Vertical tube: **5**, 292-305

Water cooling panel system: **3**, 159-175
Wick: **8**, 528-540
Wire: **4**, 291-235
Working substrate: **1**, 1-15